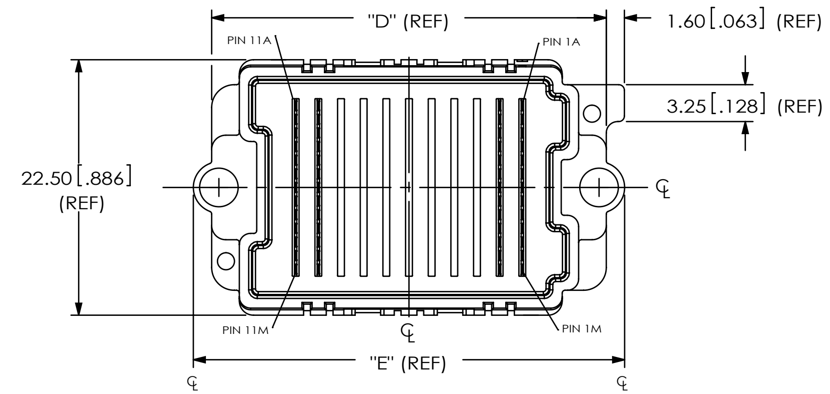
REVISION F

DO NOT
SCALE FROM
THIS PRINT

DESIGNED & DIMENSIONED IN MILLIMETERS (INCHES FOR REFERENCE ONLY)



HDAM-XX-XX.X-X-13-X-XX

No OF POSITIONS
(13 ROW PER POSITION)
-11
-15
-23

LEAD STYLE
-12.0: 12MM
-17.0: 17MM

PLATING SPECIFICATION
-S: 30 µ" SELECTIVE GOLD IN MATING AREA,
MATTE TIN ON TAIL AND GUIDE PINS

No OF ROWS
-13

SOLDER CHARGE MATERIAL
-1: 63%TIN / 37% LEAD
-2: 95.5% TIN / 3.8% SILVER
0.7% COPPER (LEAD FREE)

OPTION
-P: PICK & PLACE PAD
(USE MPP-26-01-N)
-TR: TAPE & REEL
(ONLY TOOLED FOR HDAM-23-12.0-X-13-X)

TABLE 1

STYLE	"BODY CALLOUT"	"TERMINAL WAFER"	"GUIDE PIN"
-12.0	HDAM-XX-12.0	SUB-IM-T-1M35-12.0-S-X	WT-24-12.0-T
-17.0	HDAM-XX-17.0	SUB-IM-T-1M35-17.0-S-X	WT-24-17.0-T

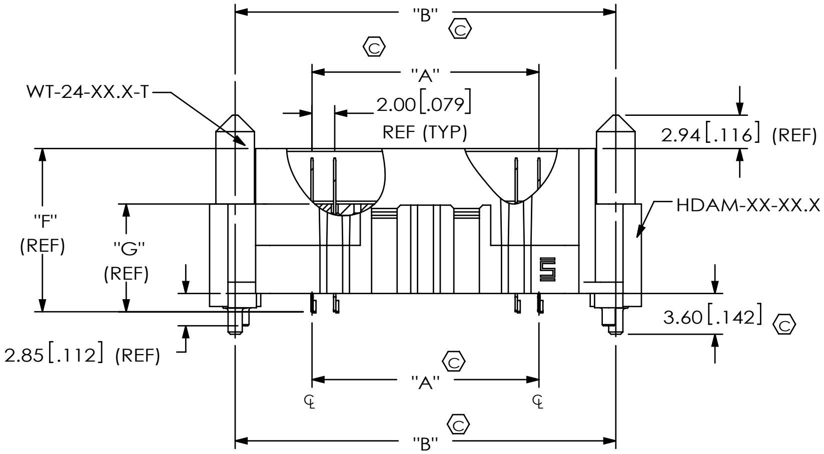


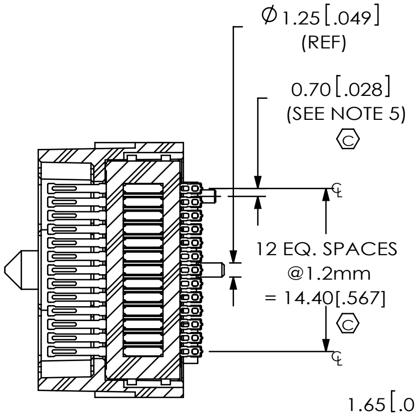
TABLE 2

STACK HEIGHT

HDAM LEAD STYLE	HDAF LEAD STYLE	
	-08.0	-18.0
-12.0	20.0MM	30.0MM
-17.0	25.0MM	35.0MM

TABLE 3

No. OF POS.	LEAD STYLE	"A"	"B"	"C"	"D"	"E"	"F"	"G"
11	12	20.0 [.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371	38.06 [1.498]	14.41 [.567]	9.51 [.374]
15	12	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	14.41 [.567]	9.51 [.374]
23	12	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.443]	14.41 [.567]	9.51 [.374]
11	17	20.0 [.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371	38.06 [1.498]	19.41 [.764]	14.51 [.571]
15	17	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	19.41 [.764]	14.51 [.571]
23	17	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.443]	19.41 [.764]	14.51 [.571]



SECTION A-A

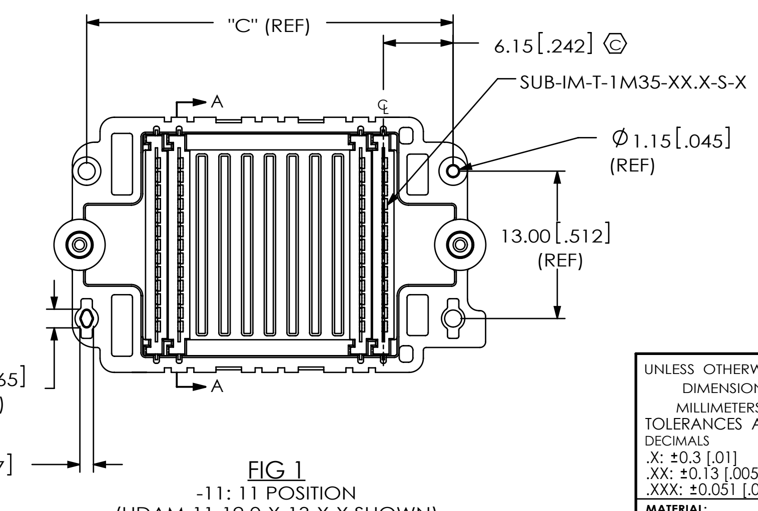
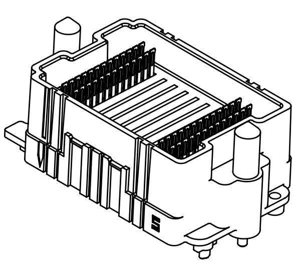
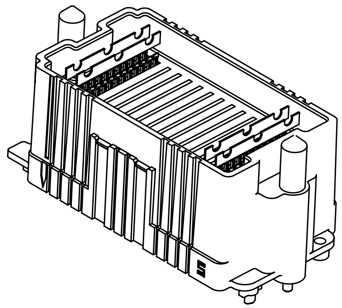


FIG 1
-11: 11 POSITION
(HDAM-11-12.0-X-13-X-X SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)



(-12.0 SHOWN)



(-17.0 SHOWN)

NOTES:

1. Ⓒ REPRESENTS A CRITICAL DIMENSION.
2. MINIMUM PUSHOUT FORCE: 2.22N[.5 LB]. FOR WAFERS
3. CONNECTORS TO BE PACKAGED IN TRAYS IF -TR OPTION IS NOT SELECTED, -TR OPTION IS ONLY TOOLED FOR HDAM-23-12.0-X-13-X.
4. USE THESE SURFACES TO MEASURE "G" DIMENSION.
5. DIMENSION FROM ℄ OF END TAIL TO ℄ OF -A PIN.

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN
MILLIMETERS [INCHES].
TOLERANCES ARE:

DECIMALS	ANGLES
.X: ±0.3 [.01]	2 °
.XX: ±0.13 [.005]	
.XXX: ±0.051 [.0020]	

samtec
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MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 1.5:1

INSULATOR: LCP, COLOR: BLACK
CONTACT: COPPER ALLOY
WAFER MATERIAL: LCP, COLOR: BLACK
GUIDE PIN MATERIAL: BRASS
PICK AND PLACE PAD: COPPER ALLOY

DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-XX

BY: D KNOWLDEN 7/15/2005
SHEET 1 OF 3

REVISION F

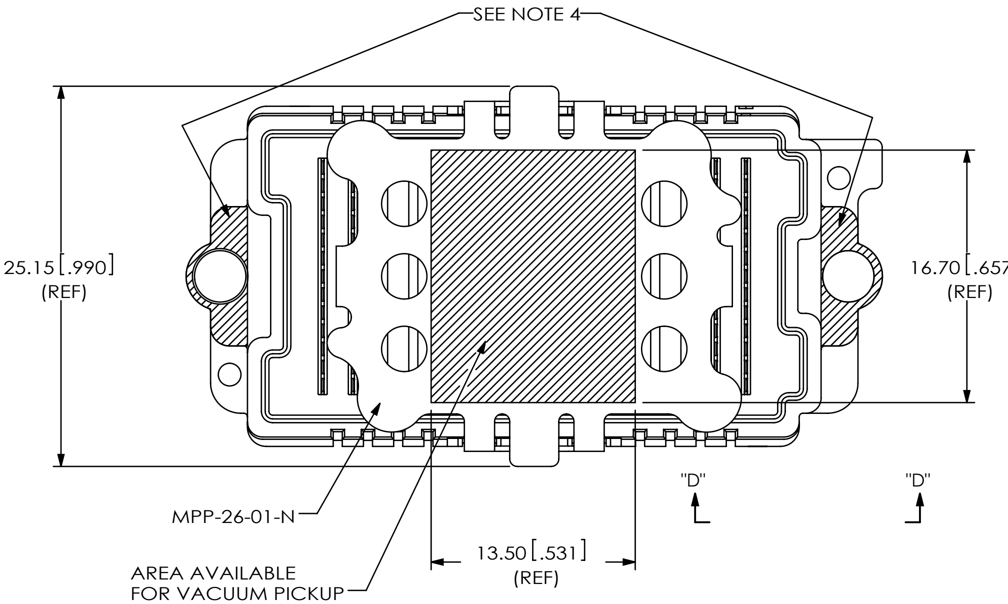
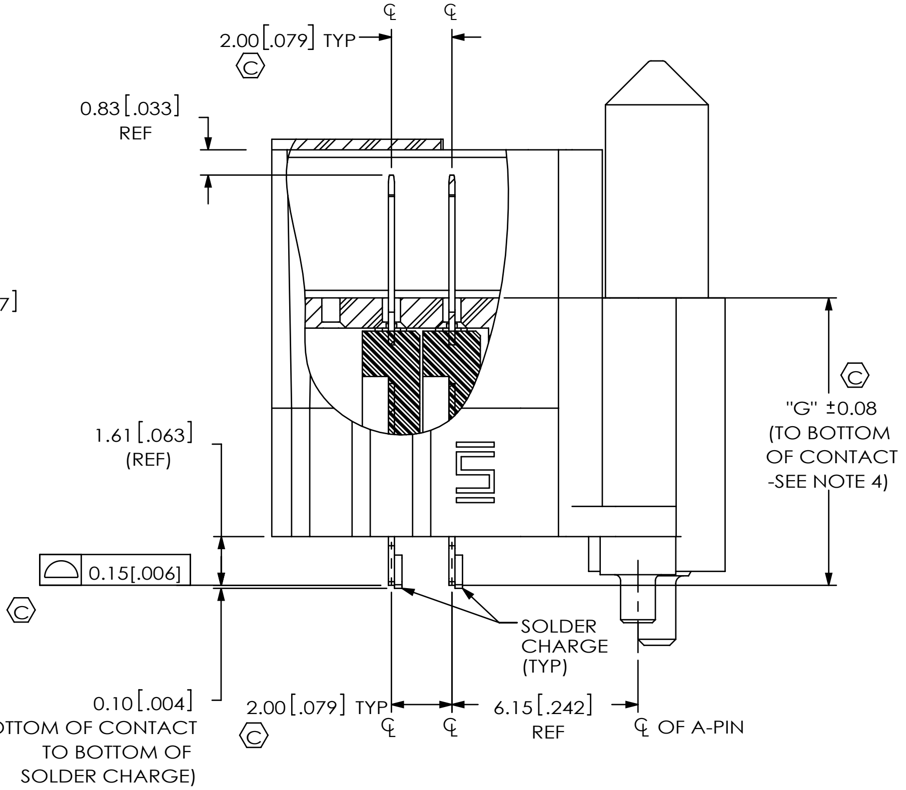


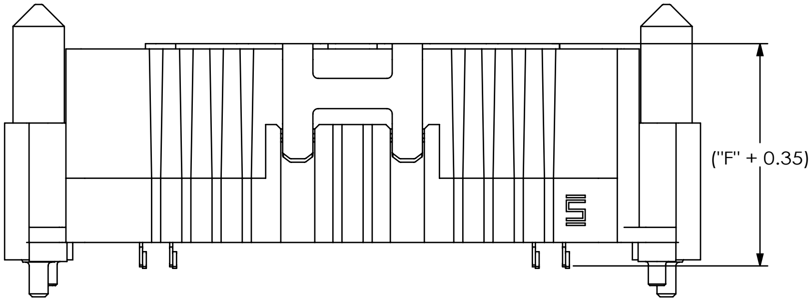
FIG 2

-15: 15 POSITION

(HDAM-15-12.0-X-13-X-P SHOWN)

(SOME WAFERS NOT SHOWN FOR CLARITY)





VIEW D-D

SCALE 4:1

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DO NOT SCALE DRAWING

SHEET SCALE: 2:1

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520 PARK EAST BLVD, NEW ALBANY, IN 47150
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e-Mail info@SAMTEC.com code 55322

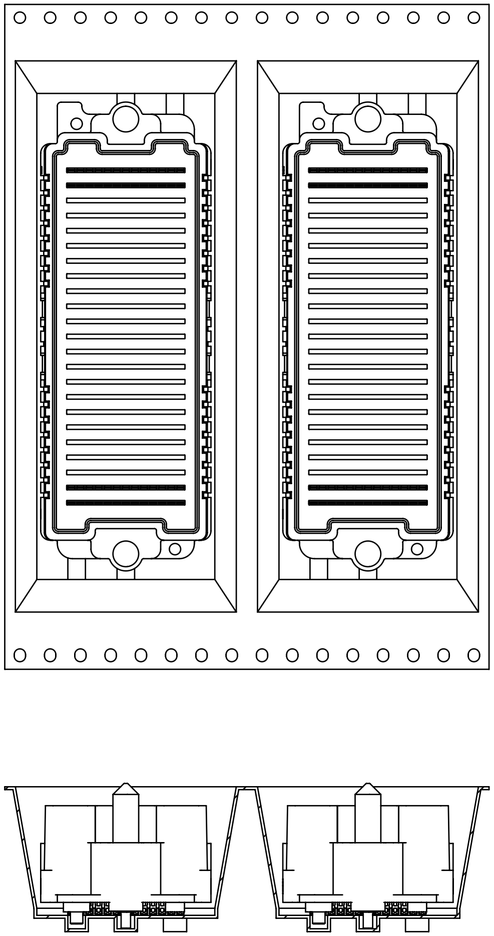
DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-XX

BY:D KNOWLDEN 7/15/2005 SHEET 2 OF 3

F:\DWG\MISC\MKTG\HDAM-XX-XX.X-X-13-X-XX-MKT.SLDDRW

REVISION F



USER DIRECTION OF UNREELING →

POCKET NOT DETAILED

-TR PACKAGING VIEW

(ONLY TOOLED FOR HDAM-23-12.0-X-13-X)

F:\DWG\MISC\MKTG\HDAM-XX-XX.X-X-13-X-XX-MKT.SLDDRW

DO NOT SCALE DRAWING

SHEET SCALE: 1:1

samtec
520 PARK EAST BLVD, NEW ALBANY, IN 47150
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e-Mail info@SAMTEC.com code 55322

DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-XX

BY: D KNOWLDEN 7/15/2005 SHEET 3 OF 3